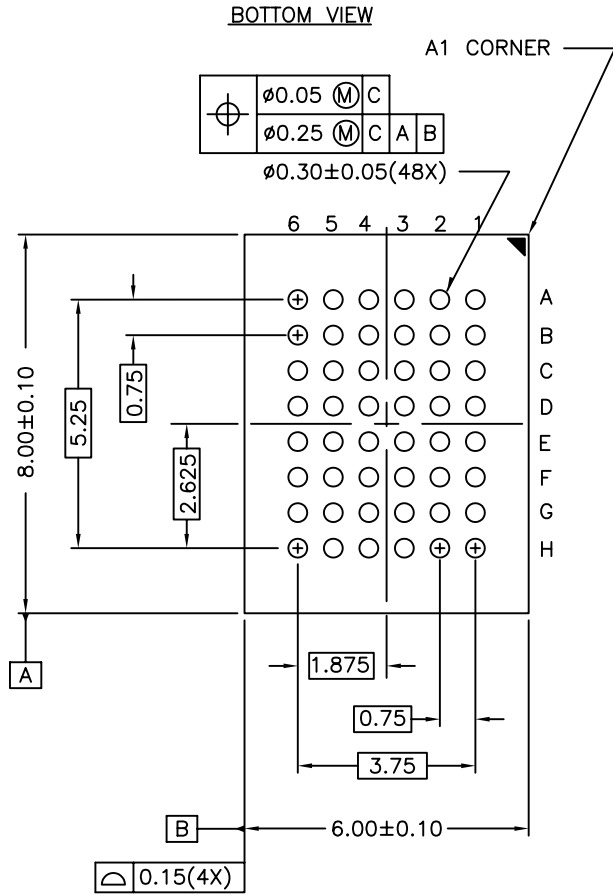
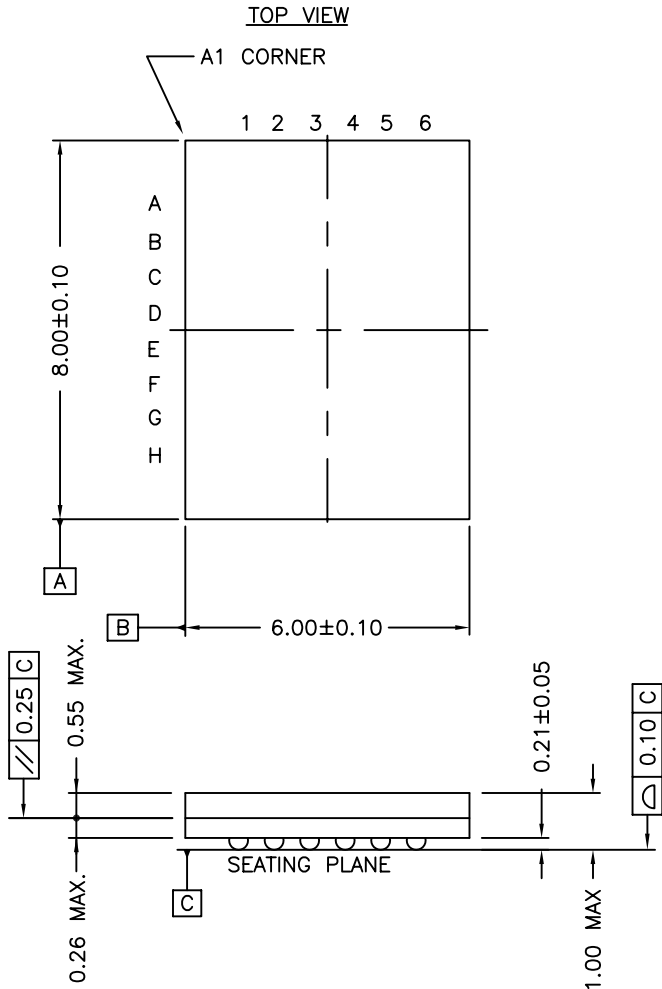


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	111203	CREATED DWG TEMPLATE	10/29/01	
		*A	118367	CHG. PKG. BODY TOLERANCE/ADD MOLD CAP & SUBSTRATE DIM./CHG. LEAD COPLANARITY & BALL HEIGHT	08/28/02	
		*B	121987	CHG. MOLD CAP DIM. & SUBSTRATE DIM./ CHG. TITLE	11/26/02	
		*C	391420	CHG. COPLANARITY FROM 0.15 TO 0.10	08/11/05	
		*D	395148	CHG PKG CODE FROM BV48A TO BV	09/02/05	
		*E	2780421	CHANGE DRAWING FORMAT & CHANGE TITLE FROM 48 VFBGA 6X8X1.0 MM PACKAGE OUTLINE TO PACKAGE OUTLINE, 48L VFBGA 6X8X1.0 MM BV48/BZ48	10/07/09	BZG
		*F	3013601	Change N.A. to Production on the Status Bar.	08/25/10	AWP
		*G	3362447	Update for sunset review, no changed	09/05/11	QAD
1		*H	3740076	Added "Package Weight: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress web".	09/11/12	QAD



NOTE:  
PACKAGE WEIGHT: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress web.

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°	DESIGNED BY HTN	DATE 10/07/09									
	DRAWN BY HTN	DATE 10/07/09									
	CHECKED BY EDCA	DATE 09/11/12									
	APPROVED BY QAD	DATE 09/11/12									
MATERIAL DEFAULT TEXT	APPROVED BY CMG	DATE 09/11/12	TITLE PACKAGE OUTLINE, 48L VFBGA 6X8X1.0 MM BV48/BZ48								
FINISH DEFAULT TEXT	APPROVED BY RODP	DATE 09/11/12	<table border="1"> <tr> <td>SIZE A</td> <td>PART NO. BV48/BZ48</td> <td>DWG NO. 51-85150</td> <td>REV *H</td> </tr> <tr> <td>SCALED TO FIT</td> <td>PRODUCTION</td> <td>SHEET 1 OF 1</td> <td></td> </tr> </table>	SIZE A	PART NO. BV48/BZ48	DWG NO. 51-85150	REV *H	SCALED TO FIT	PRODUCTION	SHEET 1 OF 1	
SIZE A	PART NO. BV48/BZ48	DWG NO. 51-85150	REV *H								
SCALED TO FIT	PRODUCTION	SHEET 1 OF 1									

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